### Overview

HP EliteBook 735 G6 Notebook PC



- 1. HD and IR Camera (Optional)
- 2. Ambient Light Sensor (Optional)
- 3. IR Camera LEDs (Optional)
- 4. Internal Microphones
- 5. HP Privacy Camera Shutter
- 6. HD Camera LED

- Left
- 7. Clickpad
- 8. Smartcard Reader (Optional)
- 9. USB 3.2 Gen 1 Charging Port
- 10. Vents
- 11. Nano Security Lock Slot (Lock sold separately)
- 12. Power Button



### **Overview**



Right

- Power Connector 1.
- USB Type-C™ 2.
- **Docking Connector** 3.
- **Ethernet Port** 4.
- HDMI Port (Cable not included) 5.

- 6. USB 3.2 Gen 1 port
- 7. Audio Combo Jack
- 8. SIM Card Slot<sup>1</sup>
- 9. Touch Fingerprint Sensor (Optional)
- **10.** Pointstick

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug



### **Overview**

AT A GLANCE

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel
- Choice of 2nd Generation AMD® Ryzen™ PRO processors
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt™ dock.<sup>1</sup> The 735 notebooks connect to the Thunderbolt docks via USB-C alt-mode.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ant-glare touch displays with ambient light sensor
- Choice of displays:
   33.8 cm (13.3") diagonal FHD IPS anti-glare LED-backlit, non-touch, 250 nits, 45% NTSC
   33.8 cm (13.3") diagonal FHD IPS anti-glare LED-backlit non-touch 400 nits, 72% NTSC
   33.8cm (13.3") diagonal FHD IPS anti-glare LED-backlit non-touch, 1000 nits, 72% NTSC with HP Sure View<sup>6</sup>
   33.8cm (13.3") diagonal FHD Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
- Enterprise grade security with HP SureStart, HP Privacy Camera<sup>1</sup>, HP Sure View<sup>4</sup>, HP Sure Run, HP Sure Recover, HP Sure Click, HP Sure Sense<sup>5</sup>, SmartCard Reader<sup>1</sup> and Touch Fingerprint reader<sup>1</sup>
- Preinstalled with Windows 10 versions or FreeDOS
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles<sup>2</sup>
- Enables AMD Memory Guard to help defend against cold boot attacks with real-time encryption and decryption of system's memory
- Flexible wireless connectivity options
- Passed MIL-STD 810G tests<sup>3</sup>
- Battery Life up to 15 hours and 15 minutes (2<sup>nd</sup> Gen AMD<sup>®</sup> Ryzen<sup>™</sup> PRO APU processor, 13.3" 400 nits panel and 3-cell 50WHr battery)

#### 1. Sold separately or as an optional feature.

2. HP Elite notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

3. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

4. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation. Available in Q3'19.

5. HP Sure Sense requires Windows 10. See product specifications for availability.

6. Touch-enabled display and Sure View privacy panel will lower actual brightness

NOTE: See important legal disclosures for all listed specs in their respective features sections.



### Features

**PRODUCT NAME** 

HP EliteBook 735 G6 Notebook PC

#### OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64<sup>1</sup> Windows 10 Pro 64 (National Academic License)<sup>2</sup> Windows 10 Home 64<sup>1</sup> Windows 10 Home Single Language 64<sup>1</sup> Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)<sup>1</sup> FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on http://www.support.hp.com.

#### PROCESSORS

AMD Ryzen™ 7 PRO 3700U APU with Radeon™ Vega 10 Graphics (2.3 GHz base clock, up to 4 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

AMD Ryzen™ 5 PRO 3500U APU with Radeon™ Vega 8 Graphics (2.1 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

AMD Ryzen™ 3 PRO 3300U APU with Radeon™ Vega 6 Graphics (2.1 GHz base clock, up to 3.5 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

Processor Family 2nd Gen AMD® Ryzen™ PRO APU processor⁵

3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

5. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

#### CHIPSET

Chipset is integrated with processor



### Features

#### GRAPHICS

Integrated AMD Radeon™ Vega Graphics<sup>6</sup>

Supports
Support HD decode, DX12, and HDMI2.0

6. HD content required to view HD images.

#### DISPLAY

Non-Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC for WWAN (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim with HP Sure View Integrated Privacy Screen, 1000 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera for WWAN (1920 x 1080)<sup>6,7,8,9,46</sup>

#### Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC, with HD+IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

HDMI 2.0
Support resolution up to 4k @ 60Hz

6. HD content required to view HD images.

7. HP Sure View Gen3 integrated privacy panel is an option feature that must be configurated at purchase and is designed to function in landscape orientation. Available in Q3'19.

8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

9. Sold separately or as an optional feature.

46. Touch-enabled display and Sure View privacy panel will lower actual brightness



### Features

Docking station model	Total number of supported displays (incl. the notebook display)	Max.resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station	4	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays into DP
HP Thunderbolt Dock G2	4	Dual 2560 x 1600 @ 60Hz Single 3840 x 2160 @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	
HP Elite USB-C Dock G4	4	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

#### STORAGE AND DRIVES

```
Primary M.2 Storage

128 GB SATA-3 SS TLC<sup>10</sup>

256 GB PCIe<sup>®</sup> NVMe<sup>™</sup> Value SS TLC<sup>10</sup>

256 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC<sup>10</sup>

256 GB SATA-3 TLC Opal 2<sup>10</sup>

512 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC<sup>10</sup>

512 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC Opal 2<sup>10</sup>

512 GB PCIe<sup>®</sup> Value<sup>10</sup>

1 TB PCIe<sup>®</sup> Gen3 x4 NVMe<sup>™</sup> SS TLC<sup>10</sup>
```

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

#### MEMORY

```
Maximum Memory
32 GB DDR4-2400 SDRAM
```

```
Memory
32 GB DDR4-2400 SDRAM (2 x 16 GB)<sup>11</sup>
16 GB DDR4-2400 SDRAM (1 x 16 GB)<sup>11</sup>
16 GB DDR4-2400 SDRAM (2 x 8 GB)<sup>11</sup>
```



### Features

8 GB DDR4-2400 SDRAM (1 x 8 GB)<sup>11</sup> 8 GB DDR4-2400 SDRAM (2 x 4 GB)<sup>11</sup> 4 GB DDR4-2400 SDRAM (1 x 4 GB)<sup>11</sup>

Memory Slots 2 SODIMM Both slots are customer accessible / upgradeable DDR4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

#### NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro<sup>™12</sup> Intel® AX200 Wi-Fi 6<sup>16</sup> (2x2) and Bluetooth® 5 Combo, non-vPro<sup>™</sup> (supporting gigabit file transfer speeds) Realtek RTL8822BE 802.11ac (2x2) and Bluetooth® 4.2 Combo<sup>12</sup>

WWAN Intel® XMM™ 7360 LTE-Advanced Cat 9<sup>13</sup>

NFC NXP NPC300 Near Field Communication Module

Miracast Native Miracast Support<sup>14</sup>

Ethernet Realtek PCIe GbE Family Controller 10/100/1000<sup>15</sup>

12. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

13. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

14. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming. 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

AUDIO/MULTIMEDIA

*Audio* Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers



### Features

Camera 720p HD camera<sup>6,9</sup> 720p HD+IR camera<sup>6,9,17</sup>

Sensors Ambient light sensor (Select models only) Hall Sensor

6. HD content required to view HD images.9. Sold separately or as an optional feature.17. Internet access required.

#### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

#### Keyboard

HP Premium Collaboration Keyboard, spill resistant with drain Backlit keyboard available as an option

Pointing Device Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

- Function Keys F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - numlk F11 - Wireless F12 - Calendar Share/Present **Call Answer Call End** Hidden Function Keys Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock Fn+E - Insert
- Fn +W Pause



### Features

SOFTWARE AND SECURITY

Preinstalled Software BIOS HP BIOSphere Gen5<sup>18</sup> HP Drive Lock & Automatic Drive Lock<sup>19</sup> BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase<sup>20</sup> Absolute Persistence Module<sup>21</sup>

**Pre-boot Authentication** 

#### Software

HP Native Miracast Support<sup>22</sup> HP Connection Optimizer HP Image Assistant HP Hotkey Support HP JumpStart HP Support Assistant<sup>23</sup> HP Noise Cancellation Software Buy Office (Sold separately)

#### Manageability Features

HP Driver Packs<sup>24</sup> HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen3<sup>25</sup> HP Cloud Recovery<sup>26</sup>

#### **Client Security Software**

HP Client Security Manager Gen5<sup>27</sup> HP Fingerprint Sensor<sup>28</sup> HP Power On Authentication Windows Defender<sup>29</sup>

### Security Management Pre-boot Authentication TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)<sup>30</sup> SATA 0,1 port disablement (via BIOS) USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS)



### Features

Support for chassis padlocks and cable lock devices HP Sure Click<sup>31</sup> HP Sure Start For AMD<sup>32</sup> Sure Run Gen2<sup>33</sup> Sure Recover Gen2<sup>34</sup> Sure Sense<sup>35</sup>

Security

TPM Model: Infineon SLB9670 Version: 7.85 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes (select models only)

Smartcard Reader Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Certification:

Yes/No

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

**Graphics (Intel Video Driver): TBD** 

WWAN: TBD

WLAN: TBD

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

18. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

19. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

20. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

21. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

22. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



### Features

23. HP Support Assistant requires Windows and Internet access.

24. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

25. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

26. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630

27. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.

28. HP Fingerprint Sensor sold separately or as an optional feature.

29. Windows Defender Opt in and internet connection required for updates.

30. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).re TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

31. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

32. HP Sure Start for AMD is available on select HP PCs with AMD processors. See product specifications for availability. 33. HP Sure Run Gen2: See product specifications for availability.

34. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.

35. HP Sure Sense requires Windows 10. See product specifications for availability.



### Features

POWER

#### Power Supply

```
HP Smart 45 W External AC power adapter<sup>36</sup>
HP Smart 45 W External AC power adapter, 2-prong (Japan only)<sup>36</sup>
HP Smart 65 W External AC power adapter<sup>36</sup>
HP Smart 65 W EM External AC power adapter<sup>36</sup>
45 W USB Type-C<sup>™</sup> adapter<sup>36</sup>
65 W USB Type-C<sup>™</sup> adapter<sup>36</sup>
```

Primary Battery HP Long Life 3-cell, 50 Wh Li-ion<sup>37, 38</sup> Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)<sup>37, 38</sup>

#### Battery Life

Battery Life up to 15 hours and 15 minutes (2<sup>nd</sup> Gen AMD® Ryzen™ PRO APU processor, 13.3" 400 nits panel and 3-cell 50WHr battery)<sup>39</sup>

#### Power Cord

```
2-wire plug - 1.0m<sup>36</sup>
3-wire plug - 1.0m<sup>36</sup>
3-wire plug - 1.8m<sup>36</sup>
Duckhead power cord - 1.0m<sup>36</sup>
Duckhead power cord - 1.8m<sup>36</sup>
```

36. Availability may vary by country.

37. Battery is internal and not replaceable by customer. Serviceable by warranty.

38. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging

time may vary +/-10% due to System tolerance.

39. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

#### WEIGHTS & DIMENSIONS

Weight

Starting at 2.94 lb (non-touch); Starting at 3.18 lb (touch)<sup>40</sup> Starting at 1.33 kg (non-touch); Starting at 1.44 kg (touch)<sup>40</sup>

Product Dimensions (w x d x h) Non-Touch 12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.77 cm

Touch 12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.79 cm

40. Weight will vary by configuration.



### Features



### Features

PORTS/SLOTS

Ports 1 USB Type-C™ (Alt Mode) 2 USB 3.2 Gen 1 (1 charging) 1 HDMI 2.0<sup>41</sup> 1 RJ-45 / Ethernet 1 Docking connector 1 Headphone/microphone combo 1 AC power 1 SIM card slot<sup>42</sup> 1 Smartcard reader<sup>42</sup>

41. HDMI cable sold separately. 42. Sold separately or as an optional feature.

#### SERVICE AND SUPPORT

HP Services offers 1-year or 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.<sup>43</sup>

43. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



### Features



### **Technical Specifications**

### ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:			
	• IT ECO declaration	or these marks.		
	• US ENERGY STAR®			
	-	United States. Based on US EPEAT varies by country. See http://www		
	information.			
System Configuration	The configuration used for the E Notebook model is based on a Ty	nergy Consumption and Declared pically Configured Notebook.	Noise Emissions data for the	
Energy Consumption				
(in accordance with US				
ENERGY STAR <sup>®</sup> test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
		·		
Normal Operation (Short idle)	7.69 W	7.72	7.46	
Normal Operation	5.88 W	6.11	5.88	
(Long idle)				
Sleep	0.79 W	0.83	0.78	
Off	0.40 W	0.43	0.41	
	Energy efficiency data listed is	for an ENERGY STAR® compliant	product if offered within the	
		arked with the ENERGY STAR® I		
		Protection Agency (EPA) ENER	-	
	-	loes not offer ENERGY STAR® co or a typically configured PC featu		
		icrosoft Windows® operating syst		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	26 BTU/hr	26 BTU/hr	25 BTU/hr	
(Short idle)				
Normal Operation	20 BTU/hr	21 BTU/hr	20 BTU/hr	
(Long idle)				
Sleep	3 BTU/hr	3 BTU/hr	2 BTU/hr	
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr	
	Heat dissipation is calculated l	based on the measured watts, a	ssuming the service level i	
	attained for one hour.			



Declared Noise		Sound Power	Sound Pressure
Emissions		(L <sub>wad</sub> , bels)	(L <sub>pAm</sub> , decibels)
(in accordance with			
ISO 7779 and ISO 9296)			
Typically Configured –		2.5	15
Idle			
Fixed Disk – Random		3	23
writes			
Longevity and Upgrading	features an • 3 USB port • 1 PC card s • 1 Express • 1 IEEE 139 • 2 SODIMM • Optional e • 1 multi-ba • Interchan	d/or components contained in the pr s slot (type I/II) Card/54 slot 4 Port memory slots expansion base docking station by II storage port geable HDD are available throughout the warran	ng its useful life by several years. Upgradeable oduct may include: nty period and or for up to "5" years after the
Batteries	Batteries us Mercury gre Cadmium gr Battery size	y(s) in this product comply with EU D sed in the product do not contain: eater the1ppm by weight reater than 20ppm by weight e: CR2032 (coin cell)	irective 2006/66/EC
Additional Information	2011/65/E0 • This HP pr	ict is in compliance with the Restrict	ions of Hazardous Substances (RoHS) directive - Waste Electrical and Electronic Equipment
	<ul> <li>This produce</li> <li>Water and T</li> <li>This produce</li> <li>This produce</li> <li>New Plastics periods</li> <li>ISO1043.</li> <li>This produce</li> </ul>	act is in compliance with California P Toxic Enforcement Act of 1986). Act is in compliance with the IEEE 168 Acepeat.net	• • • •
Packaging Materials	External:	PAPER/Corrugated	261 g
	Internal:	PLASTIC/EPE (Expanded Polyethy	lene) 63 g
		PLASTIC/Polypropylene - PP PLASTIC/Polyethylene low densit	3 g
Material Usage	(refer to the http://www • Asbestos		ng substances in excess of regulatory limits vironment at



r	
	<ul> <li>Certain Brominated Flame Retardants – may not be used as flame retardants in plastics</li> <li>Cadmium</li> </ul>
	• Chlorinated Hydrocarbons
	• Chlorinated Paraffins
	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	• Lead and Lead compounds
	• Mercuric Oxide Batteries
	• Nickel – finishes must not be used on the external surface designed to be frequently handled
	or carried by the user.
	Ozone Depleting Substances
	<ul> <li>Polybrominated Biphenyls (PBBs)</li> </ul>
	<ul> <li>Polybrominated Biphenyl Ethers (PBBEs)</li> </ul>
	<ul> <li>Polybrominated Biphenyl Oxides (PBBOs)</li> </ul>
	<ul> <li>Polychlorinated Biphenyl (PCB)</li> </ul>
	<ul> <li>Polychlorinated Terphenyls (PCT)</li> </ul>
	<ul> <li>Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been</li> </ul>
	voluntarily removed from most applications.
	Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	<ul> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> </ul>
	<ul> <li>Design packaging materials for ease of disassembly.</li> </ul>
	<ul> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> </ul>
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	<ul> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> </ul>
	<ul> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas.
and Recycling	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your
	nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a
	responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information
	for each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP
	OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	Global Citizenship Report
Information	טנטטמו כונוצבווטווף הבףטו נ
	http://www.hp.com/hpinfo/globalcitizenship/generate/index.html
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www.0.hp.com/we/en/hp.information/environment/contatestatestate
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html



### **Technical Specifications**

ISO 14001 certificates:
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_ 14K_Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

#### SYSTEM UNIT

Stand-Alone Power	Nominal Operating Voltage	2 <b>19V</b>
Requirements (AC Power)	Average Operating Power	Win 10
	Integrated Graphics	AMD has no this data (APU is 15 W)
	Max Operating Power	UMA <45 W
Temperature	Operating	32° to 95° F (0° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	UL	Yes
Certifications	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR <sup>®</sup>	Yes, Select models <sup>44</sup>
	EPEAT® 2019	Yes, Silver in U.S. <sup>45</sup>
	Australia / NZ A-Tick Compliance	Yes
	<i>CCC</i>	Yes
	Japan VCCI Compliance	Yes
	КС	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	GOST	Yes
	Saudi Arabian Compliance (ICCP)	Yes
	UKRSERTCOMPUTER	Yes

44. Configurations of the HP Elitebook 735 G6 that are ENERGY STAR<sup>®</sup> certified are identified as HP Elitebook 735 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.
45. Based on US EPEAT<sup>®</sup> registration according to IEEE 1680.1-2018 EPEAT<sup>®</sup>. Status varies by country. Visit http://www.epeat.net for more information.



### **Technical Specifications**

### DISPLAYS

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP 1.2 w/o PSR slim NWBZ

Outline Dimensions (W x H)	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
Active Area	293.76 x 165.24 mm (typ.)
Weight	260 g (max)
Diagonal Size	13.3 inch
Thickness	3.0 mm (max)
Interface	eDP 1.2 (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	600:1 (typ.)
Refresh Rate	60 Hz
Brightness	250 nits (typ.)
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	45% NTSC
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim Touch on Panel Narrow Bezel

Outline Dimensions (W x H)	300.56 x 187.77
Active Area	293.76 x 165.24 mm (typ.)
Weight	268 g (max)
Diagonal Size	13.3 inch
Thickness	3.2mm (max)
Interface	eDP 1.2
Surface Treatment	Anti-Glare On-cell
Touch Enabled	Yes
Contrast Ratio	600:1 (typ.)
Refresh Rate	60 Hz
Brightness	250 nits
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	45% NTSC
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85



### **Technical Specifications**

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP 1.4+PSR2 Ultraslim Narrow Bezel

Outline Dimensions (W x H)	299.06 x 185.54 mm (max)
Active Area	293.76 x 165.24 mm (typ.)
Weight	170 g (max)
Diagonal Size	13 inch
Thickness	2.0 mm (max)
Interface	eDP 1.4 + PSR2 (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	72% NTSC
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch FHD (1920 x 1080) Anti-Glare WLED UWVA 72percent cg 1000nits eDP 1.4+PSR2 flat Privacy NWBZ\* Outline Dimensions (W x H) 299.06 x 186.54 mm (max) Active Area 293.76 x 165.24 mm (typ.) Weight 255 g (max) 13.3 inch **Diagonal Size** Thickness 3.0 mm (max) Interface eDP 1.4 + PSR2 (4 lane) Surface Treatment **Bright-View (BV)** Touch Enabled No Contrast Ratio 2000:1 (typ.) **Refresh Rate** 60 Hz Brightness\*\* 1000 nits Pixel Resolution 1920 x 1080 (FHD) Format of LCD Pixel Arrangement RGB **Backlight** LED Color Gamut Coverage 72% NTSC Color Depth 8 bits Viewing Angle UWVA 85/85/85/85

\*Available in Q3'19

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

\*\*Touch-enabled display and Sure View privacy panel will lower actual brightness



### **Technical Specifications**

### STORAGE

SSD 128 GB 2280 M2 SATA-3 TLC	Form Factor	M.2 2280
330 120 GB 2200 H2 3HH1 3 120	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 540 ~ 560 MB/s
	Maximum Sequential Write	Around 380 ~ 530 MB/s
	Logical Blocks	250069680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP
SSD 1 TB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280
Three Layer Cell single-sided	Capacity	1 TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 3200 ~ 3480 MB/s
	Maximum Sequential Write	
	Logical Blocks	2000409264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 256 GB 2280 M2 PCIe-3x4 SS	Form Factor	M.2 2280
NVMe TLC	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3167 MB/s
	Maximum Sequential Write	Around 1300 ~ 1663 MB/s
	Logical Blocks	500118192



32° to 158°F (0° to 70°C) [ambient temp]

Operating Temperature

	Features	ATA Security; TRIM; L1.2
SSD 256 GB 2280 M2 SATA-3 Self	Form Factor	M.2 2280
Encrypted OPAL2 Three Layer	Capacity	256 GB
Cell	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 530 ~ 560 MB/s
	Maximum Sequential Write	Around 500 ~ 530 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP
SD 256 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 780 ~ 1300 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
5SD 512 GB 2280 M2 PCIe-3x4 SS	Form Factor	M.2 2280
NVMe TLC	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2700 ~ 3400 MB/s
	Maximum Sequential Write	Around 1390 ~ 2956 MB/s



	Logical Blocks Operating Temperature Features	1000215215 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; TRIM; L1.2
SSD 512 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	TLC/QLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 860 ~ 1500 MB/s
	Logical Blocks	1000215215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280
Self Encrypted OPAL2 Three	Capacity	512 GB
Layer Cell	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3400 MB/s
	Maximum Sequential Write	Around 1000 ~ 2500 MB/s
	Logical Blocks	1000215216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP



## **Technical Specifications**

#### **NETWORKING/COMMUNICATIONS**

Intel® 9260 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo <sup>1</sup> Non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11i IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security <sup>3</sup>	<ul> <li>IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
	Network Architecture	Ad-hoc (Peer to Peer)
	Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
	Roaming Output Power <sup>2</sup>	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum



### **Technical Specifications**

	• 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum	
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 n • Idle mode 50 mW (WL/ • Connected Standby/M • Radio disabled 8 mW	AN unassociated)
Power Management	ACPI compliant power r 802.11 compliant powe	-
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card	
	to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber <b>– Radio OFF</b> LED OFF <b>– Radio ON</b>	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available	Legacy: 0~79 (1 MHz/CH)
Channels	BLE: 0~39 (2 MHz/CH)



### **Technical Specifications**

Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Electrical Interface	USB 2.0 compliant		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable

- of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.

### **Technical Specifications**

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 4.2 Combo <sup>1</sup>	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security <sup>3</sup>	<ul> <li>IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power <sup>2</sup>	<ul> <li>802.11b: +14dBm minimum</li> <li>802.11g: +12dBm minimum</li> <li>802.11a: +12dBm minimum</li> <li>802.11n HT20(2.4GHz): +12dBm minimum</li> <li>802.11n HT40(2.4GHz): +12dBm minimum</li> <li>802.11n HT20(5GHz): +10dBm minimum</li> <li>802.11n HT40(5GHz): +10dBm minimum</li> <li>802.11ac VHT80(5GHz): +10dBm minimum</li> </ul>



### **Technical Specifications**

Power Consumption	<ul> <li>Transmit mode 2.0 W</li> <li>Receive mode 1.6 W</li> <li>Idle mode (PSP) 180 m</li> <li>Idle mode 50 mW (WL)</li> <li>Connected Standby 10</li> <li>Radio disabled 8 mW</li> </ul>	AN unassociated)
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity <sup>3</sup>	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	enclosure Two embedded dual bai	with spatial diversity, mounted in the display nd 2.4/5 GHz antennas are provided to the card communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCa	rd
Dimensions Weight Operating Voltage	Type 2230: 2.3 x 22.0 x Type 2230: 2.8g 3.3v +/- 9%	30.0 mm
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber <b>- Radio OFF</b> LED OFF <b>- Radio ON</b>	

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available	Legacy: 0~79 (1 MHz/CH)
Channels	BLE: 0~39 (2 MHz/CH)



### Technical Specifications

Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable

of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel® Wi-Fi® 6 <sup>5</sup> AX200 + BT5 (802.11ax 2 x 2, non- vPro, supporting gigabit file transfer speeds) non-vPro		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	<ul> <li>•802.11b: 1, 2, 5.5, 11 Mbps</li> <li>•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>•802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> <li>•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &amp; 160MHz)</li> <li>• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &amp; 160MHz)</li> </ul>
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security <sup>3</sup>	<ul> <li>IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points



Output Power <sup>2</sup>	<ul> <li>802.11b: +18.5dBm m</li> <li>802.11g: +17.5dBm m</li> <li>802.11a: +18.5dBm m</li> <li>802.11n HT20(2.4GHz</li> <li>802.11n HT40(2.4GHz):</li> <li>802.11n HT20(5GHz):</li> <li>802.11n HT40(5GHz):</li> <li>802.11ac VHT80(5GHz):</li> <li>802.11ac VHT160(5GHz):</li> <li>802.11ax HT40(2.4GHz):</li> </ul>	inimum inimum ): +15.5dBm minimum ): +14.5dBm minimum +15.5dBm minimum +14.5dBm minimum z): +11.5dBm minimum iz): +11.5dBm minimum
Power Consumption	<ul> <li>Transmit mode 2.0 W</li> <li>Receive mode 1.6 W</li> <li>Idle mode (PSP) 180 n</li> <li>Idle mode 50 mW (WLA</li> <li>Connected Standby 10</li> <li>Radio disabled 8 mW</li> </ul>	AN unassociated)
Power Management	ACPI and PCI Express of power saving mode	compliant power management 802.11 compliant
Receiver Sensitivity <sup>3</sup>	<ul> <li>•802.11b, 1Mbps: -93.5dBm maximum</li> <li>•802.11b, 11Mbps: -84dBm maximum</li> <li>•802.11a/g, 6Mbps: -86dBm maximum</li> <li>•802.11a/g, 54Mbps: -72dBm maximum</li> <li>•802.11n, MCS07: -67dBm maximum</li> <li>•802.11n, MCS15: -64dBm maximum</li> <li>•802.11ac, MCS0: -84dBm maximum</li> <li>•802.11ac, MCS9: -59dBm maximum</li> <li>•802.11ax, MCS11(HT40): -59dBm maximum</li> <li>•802.11ax, MCS11(VHT160): -58.5dBm maximum</li> </ul>	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCa	rd
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)



l echnical Specif	lcations		
	Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
HP Integrated Module wit	th Bluetooth 4.0/4.1/4.2/5	.0/5.1 Wireless Technolo	gy
	Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Con	npliant
	Frequency Band	2402 to 2480 MHz	
	Number of Available Channels	Legacy: 0~79 (1 MHz/CH BLE: 0~39 (2 MHz/CH)	1)
	Signaling Data Rate	Legacy: 3 Mbps signalin BLE: 1 Mbps signaling da 1. Actual throughput ma	ata rate <sup>1</sup> 0.2 Mbps
		Legacy: Synchronous Co channels	onnection Oriented links up to 3, 64 kbps, voice
			Connection Less links 2178.1 kbps/177.1 kbps 864 kbps symmetric (3-EV5)
	Transmit Power	=	ent shall operate as a Class II Bluetooth device nit power of + 9.5 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 m	W
	Bluetooth Software Supported	Microsoft Windows Blue	etooth Software
	Power Management	Microsoft Windows ACP	I, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, S	ection 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 87 Low Voltage Directive II UL, CSA, and CE Mark	
	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compl LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Direc LE L2CAP Connection Or Train Nudging & Interla BT4.2 ESR08 Complianc LE Secure Connection- E LE Privacy 1.2 –Link Lay LE Privacy 1.2 –Extende LE Data Packet Length E FAX Profile (FAX) Basic Imaging Profile (B Headset Profile (HSP) Hands Free Profile (HFP Advanced Audio Distrib	ted Advertising iented Channels ced Scan e Basic/Full ver Privacy ed Scanner Filter Policies Extension BIP)2



### **Technical Specifications**

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

Intel® XMM™ 7360 LTE- Advanced CAT9¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. WWAN is an optional feature, requires

### **Technical Specifications**

factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. 4G LTE not available on all products, in all regions.

Near Field Communications Controller (optional)	Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
	Chipset	NPC300
	System interface	12C
	NFC RF standards	ISO/IEC 14443 A
		ISO/IEC 14443 B ISO/IEC 15693
		ISO/IEC 15055
		ECMA-340 NFCIP-1 Target and Initiator
		ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD)	ISO/IEC 14443 A
	Mode(1)	ISO/IEC 14443 B
		ISO/IEC 15693 MIFARE 1K
		MIFARE 1K
		MIFARE DESFire
		FeliCa
		Jewel and Topaz cards
	Card Emulation	ISO/IEC 14443 A
	(PICC-VICC) Mode(1)	ISO/IEC 14443 B and B' MIFARE
		FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	0°C to 70°C
	Storage temperature	-20°C to 125°C
	Humidity	10-90% operating
		5-95% non-operating
	Supply Operating voltage	4.35 to 5.25 Volts
	I/O Voltage	1.8V or 3.3V
Power Consumption	Mode	Power Consumption, Typical
(Booster enable, VBAT=	Polling	710.93 mW
3.3V, VCC_BOOST = 5V)	Detected Test Tag Type 1	
	Detected Test Tag Type 7 Detected Test Tag Type 2	
	Detected Test Tag Type 3	303.70 IIIW



Detected Test Tag Type 4	312.26 mW
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Realtek RTK8111EPH	Connector	RJ-45
10/100/1000 Integrated	System Interface	PCIe + SMBus
NIC	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21- 30)
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support
		IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS)
		Large send offload and Giant send offload Receiving Side Scaling
		Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW
		1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW
		WoL Disable(S3/S4/S5): 25mW
	Power	ACPI compliant – multiple power modes
	Management	Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
		Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	RTK DASH support with appropriate RTK chipset components

### HP EliteBook 735 G6 Notebook PC



## **Technical Specifications**

#### POWER

AC Adapter 45 Watt nPFC Wall Mount USB type C	Dimensions Weight	62.0 x 62.0 x 28.5 mm unit: 220 g +/- 10 g	
Straight 1.8 m C6NS	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 15V: 87.8% 20V: 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec
		DC output	5V: 81.5%
		Hold-up time	9V: 86.7%
		Output current limit	10V: 87.5%
	Connector	Non-Standard C6	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions Weight Input	<b>95.0 x 40.0 x 26.5 mm</b> <b>unit: 200 g +/- 10 g</b> Input Efficiency Input frequency range Input AC current	87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63Hz Max. 1.4 A at 90 Vac
	Output Connector	Output power DC output Hold-up time Output current limit <b>C6</b>	45 W 19.5 V 5ms at 115 Vac input <8.0A
	Environmental Design	Operating temperature Non-operating (storage) temperature Altitude Humidity	32°F to 95°F (0°to 35°C) -4°F to 185°F (-20° to 85°C) O to 16,400 ft (0 to 5000m) 20% to 95%



	Storage Humidity	10% to 95%
Safety Certifications	Worldwide safety standa SELV; Agency approvals FCC Class B, CISPR22 Clas	e with LVD and EMC directives ords - IEC60950, EN60950, UL60950, Class1, - C-UL-US, NORDICS, DENAN, EN55022 Class B, is B, CCC, NOM-1 NYCE. ors at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong	Dimensions Weight Input	<b>95.0 x 40.0 x 26.5 mm unit: 200 g +/- 10 g</b> Input Efficiency Input frequency range Input AC current	87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 Vac
	Output	Output power DC output Hold-up time Output current limit	45W 19.5V 5ms at 115 Vac input <8.0A
	Connector	C8	
	Environmental Design	Operating temperature Non-operating (storage) temperature	32° to 95° F (0° to 35° C) -4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.
AC Adapter 65 Watt nPFC	Dimensions	74 x 74 x 28.5 mm	
USB type C Straight 1.8 m	Weight	unit: 245 g +/- 10 g	
C6NS	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
	Output	Output power	65W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	Non-Standard C6	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)



	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	5% to 95%
	Storage Humidity	5% to 95%
Safety Certifications	Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.

AC Adapter 65 Watt	Dimensions	102 x 55 x 30 mm	
Smart nPFC EM Barrel 4.5 mm New EM	Weight	unit: 250 g +/- 10 g	
4.5 IIIIII NEW EM	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0A
	Connector	C6	
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions Weight Input	90.0 x 51 x 28.5 mm unit: 230 g +/- 10 g Input Efficiency Input frequency range Input AC current	88.0 % at 115 Vac and 89.0 % at 230Vac 47 ~ 63 Hz Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0A
	Connector	C6	
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)



## **Technical Specifications**

	Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
Safety Certifications	Worldwide safety standa SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, s B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.

ns <b>L 278.7 mm</b>	L 278.7 mm x W 76.3 mm x H 7.1 mm	
193 g +/- 1	193 g +/- 10 g	
e 3cell Lithiu	3cell Lithium-Ion Polymer cell / P604883A1	
Voltage	11.55 V	
Amp-hour	capacity 4.113 Ah/ 4.330 Ah	
Watt-hour	capacity 50 Wh	
Operating (	Charging) <b>0° to 50° C</b>	
Operating (	Discharging) <b>-10° to 60° C</b>	
Based on sy	stem offering	
- NO		
	e <b>3cell Lithiu</b> Voltage Amp-hour o Watt-hour o Operating ( <b>Based on sy</b> Travel Battery	e <b>3cell Lithium-Ion Polymer cell / P604883A1</b> Voltage <b>11.55 V</b> Amp-hour capacity <b>4.113 Ah/ 4.330 Ah</b> Watt-hour capacity <b>50 Wh</b> Operating (Charging) <b>0° to 50° C</b> Operating (Discharging) <b>-10° to 60° C</b> <b>Based on system offering</b> Travel Battery No

### COUNTRY OF ORIGIN

China



### Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Cases	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Slim Ultrabook Top Load	F3W15AA
	HP Basic/Essential Backpack	H1D24AA
	HP Exec Midnight 15.6" Backpack	1KM16AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	<b>3XB94AA</b>
	HP TB Dock G2 combo cable	<b>3XB96AA</b>
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock w/4.5mm Adapter - non-flash version	3DV65AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP Adjustable Dual Display Stand	AW664AA
	HP Display and Notebook Stand II	E8G00AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U2OAA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1 JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2 <b>CE</b> 30AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA
	HP UC Wireless Duo Headset	W3K09AA



### Options and Accessories (sold separately and availability may vary by country)

	HP USB-C to USB 3.0 Adapter	N2Z63AAA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP HDMI to VGA	H4F02AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 90W Slim AC Adapter	H6Y83AA
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	1TZ86AA
Memory	HP 4GB 2400MHz DDR4 Memory	Z4Y84AA
	HP 8GB 2400MHz DDR4 Memory	Z4Y85AA
	HP 16GB 2400MHz DDR4 Memory	Z4Y86AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 256GB M2 PCIe NVME SSD TLC (2280)	1FU87AA
	HP 512GB M2 PCIe NVME SSD TLC 2280)	1FU88AA
Security	HP Docking Station Cable Lock	AU656AA
	HP Essential Combination Lock	TOY16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable lock	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA



### **Summary of Changes**

Change Log

Date of change:	Version History:		Description of change:
June 25, 2019	V1 to V2	Updated	Color Gamut
June 27, 2019	V2 to V3	Updated	Battery Life and Display Section
July 12, 2019	V3 to V4	Added	Environmental Section
September 6, 2019	V4 to V5	Updated	Nano lock slot, Storage Section and Brightness disclaimer for 1000nits
October 8, 2019	V5 to V6	Added	Enable AMD Memory in at a glance section
May 27, 2020	V6 to V7	Updated	Ports section

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